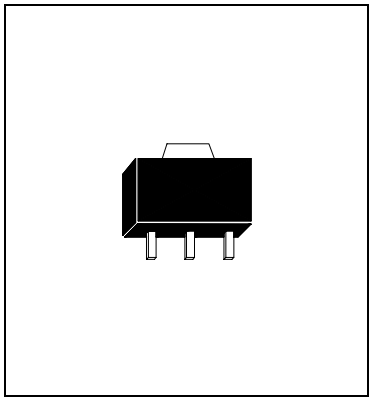
HM772A

PNP EPITAXIAL PLANAR TRANSISTOR



Description

The HM772A is designed for use in output stage of amplifier, voltage regulator, DC-DC converter and driver.

Absolute Maximum Ratings

- Maximum Temperatures
  Storage Temperature ..... -55 ~ +150 °C
  Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  Total Power Dissipation (Ta=25°C) .....1 W (Note1)
  Total Power Dissipation (Ta=25°C)..... 2 W (Note2)
  Total Power Dissipation (Ta=25°C)..... 1.5 W (Note3)
- Maximum Voltages and Currents (Ta=25°C)
  VCBO Collector to Base Voltage..... -60 V
  VCEO Collector to Emitter Voltage..... -50 V
  VEBO Emitter to Base Voltage..... -5 V
  IC Collector Current (continuous)..... -3 A
  IC Collector Current (pulse) ..... -7 A (Note4)

Note1: When tested in free air condition, without heat sinking.
Note2: When mounted on a 40X40X1mm ceramic board.
Note3: Printed circuit board 2mm thick, collector plating 1cm square or larger.
Note4: Single pulse PW=1ms

Characteristics (Ta=25°C)

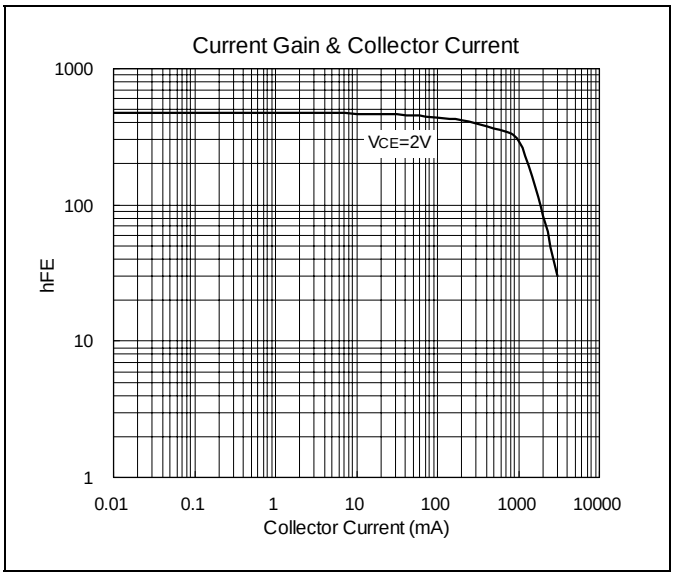
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-60	-	-	V	IC=-100uA
BVCEO	-50	-	-	V	IC=-1mA
BVEBO	-5	-	-	V	IE=-10uA
ICBO	-	-	-1	uA	VCB=-30V
IEBO	-	-	-1	uA	VEB=-3V
*VCE(sat)	-	-0.3	-0.5	V	IC=-2A, IB=-0.2A
*VBE(sat)	-	-1	-2	V	IC=-2A, IB=-0.2A
*hFE1	30	-	-		VCE=-2V, IC=-20mA
*hFE2	100	160	500		VCE=-2V, IC=-1A
fT	-	80	-	MHz	VCE=-5V, IC=-100mA, f=100MHz
Cob	-	55	-	pF	VCB=-10V, f=1MHz

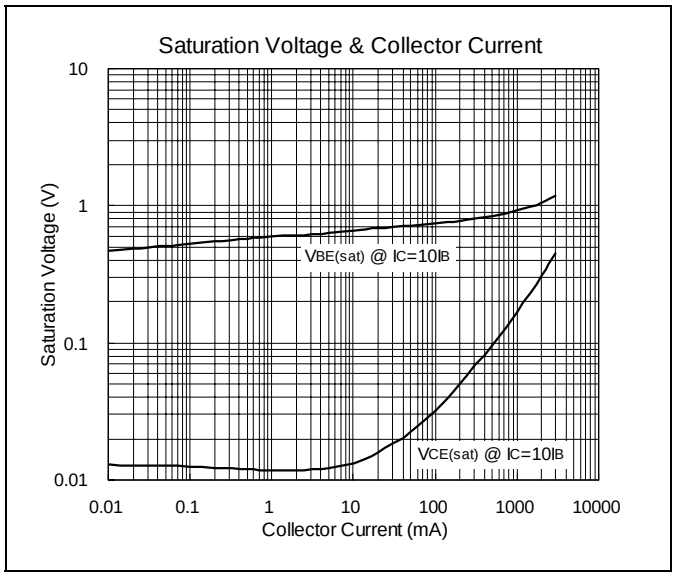
*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

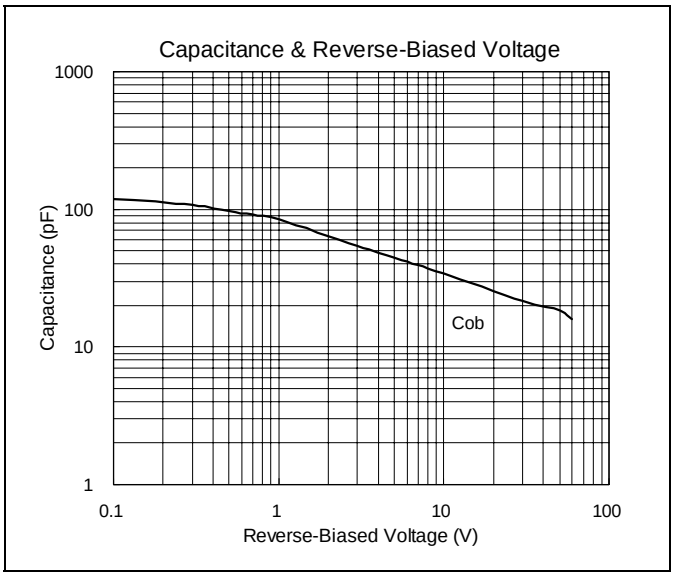
Classification Of hFE2

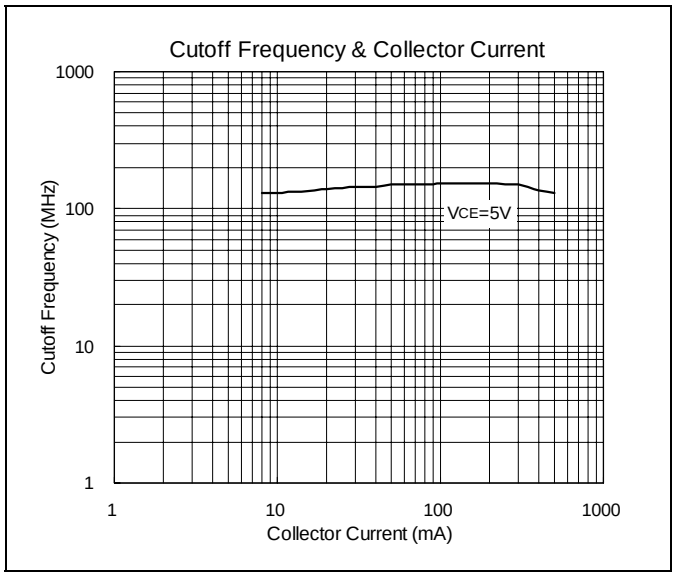
Rank	Q	P	E
Range	100-200	160-320	250-500

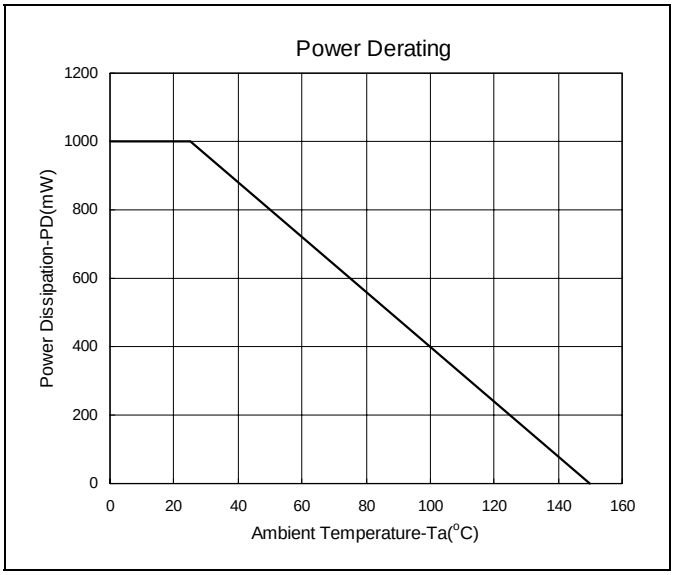
Characteristics Curve

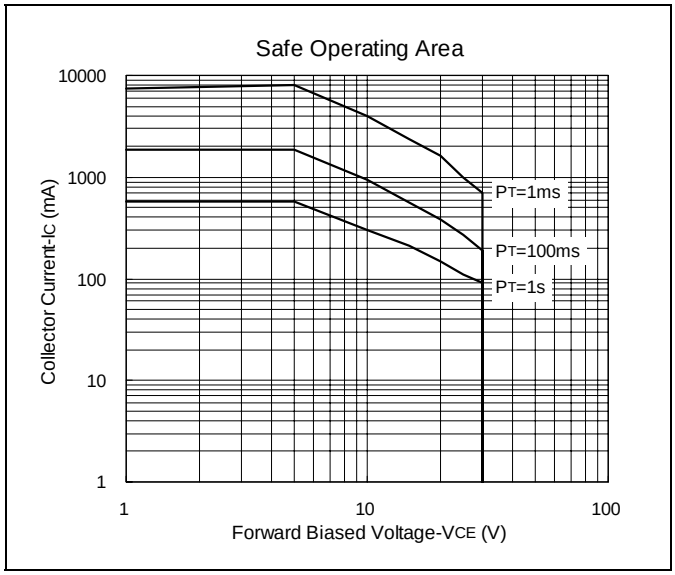




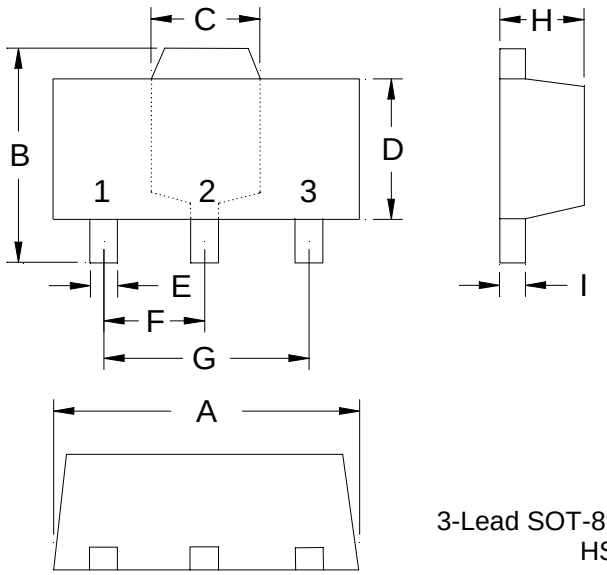




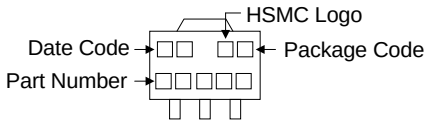




SOT-89 Dimension



Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

3-Lead SOT-89 Plastic Surface Mounted Package
HSMC Package Code : M

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.52
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.0141	0.0201	0.36	0.51					

Notes : 1.Dimension and tolerance based on our Spec. dated May. 05,1996.
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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